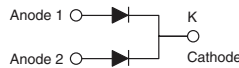
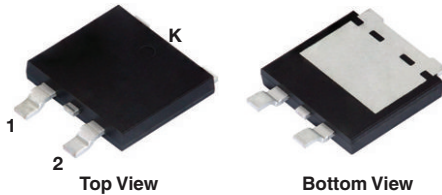


# Dual High-Voltage TMBS<sup>®</sup> (Trench MOS Barrier Schottky) Rectifier

 Ultra Low  $V_F = 0.50\text{ V}$  at  $I_F = 5.0\text{ A}$ 

## eSMP<sup>®</sup> Series SMPD (TO-263AC)



### LINKS TO ADDITIONAL RESOURCES



### FEATURES

- Trench MOS Schottky technology
- Very low profile - typical height of 1.7 mm
- Ideal for automated placement
- Low forward voltage drop, low power losses
- High efficiency operation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available:
  - Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

### TYPICAL APPLICATIONS

For use in high frequency DC/DC converters, switching power supplies, freewheeling diodes, OR-ing diode, and reverse battery protection in commercial, industrial, and automotive application.

| PRIMARY CHARACTERISTICS                                |                 |
|--|-----------------|
| $I_{F(AV)}$  | 2 x 10 A        |
| $V_{RRM}$  | 100 V           |
| $I_{FSM}$  | 130 A           |
| $V_F$ at $I_F = 10\text{ A}$ ( $T_J = 125\text{ °C}$ ) | 0.60 V          |
| $T_J$ max.   | 175 °C          |
| Package  | SMPD (TO-263AC) |
| Circuit configuration                                  | Common cathode  |

### MECHANICAL DATA

**Case:** SMPD (TO-263AC)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

**Polarity:** as marked

| MAXIMUM RATINGS ( $T_A = 25\text{ °C}$ unless otherwise noted)                     |            |             |      |
|--|------------|-------------|------|
| PARAMETER  | SYMBOL     | V20DM103C   | UNIT |
| Device marking code  |            | V20DM103C   |      |
| Maximum repetitive peak reverse voltage  | $V_{RRM}$  | 100         | V    |
| Maximum average forward rectified current (fig. 1)                                 | per device | 20          | A    |
|  | per diode  | 10          |      |
| Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load | $I_{FSM}$  | 130         | A    |
| Operating junction temperature range   | $T_J$ (2)  | -40 to +175 | °C   |
| Storage temperature range  | $T_{STG}$  | -55 to +175 |      |

#### Notes

(1) Mounted on infinite heatsink

(2) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$

| <b>ELECTRICAL CHARACTERISTICS</b> ( $T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted) |                      |                                   |             |       |      |      |
|--|----------------------|-----------------------------------|-------------|-------|------|------|
| PARAMETER  | TEST CONDITIONS      |                                   | SYMBOL      | TYP.  | MAX. | UNIT |
| Instantaneous forward voltage per diode  | $I_F = 5\text{ A}$   | $T_J = 25\text{ }^\circ\text{C}$  | $V_F^{(1)}$ | 0.57  | -    | V    |
|  | $I_F = 10\text{ A}$  |                                   |             | 0.69  | 0.76 |      |
|  | $I_F = 5\text{ A}$   | $T_J = 125\text{ }^\circ\text{C}$ |             | 0.50  | -    |      |
|  | $I_F = 10\text{ A}$  |                                   |             | 0.60  | 0.65 |      |
| Reverse current at rated $V_R$ per diode   | $V_R = 70\text{ V}$  | $T_J = 25\text{ }^\circ\text{C}$  | $I_R^{(2)}$ | 0.002 | -    | mA   |
|  |                      | $T_J = 125\text{ }^\circ\text{C}$ |             | 1.3   | -    |      |
|  | $V_R = 100\text{ V}$ | $T_J = 25\text{ }^\circ\text{C}$  |             | -     | 0.17 |      |
|  |                      | $T_J = 125\text{ }^\circ\text{C}$ |             | 3     | 9    |      |
| Typical junction capacitance   | 4.0 V, 1 MHz         |                                   | $C_J$       | 1100  | -    | pF   |

**Notes**

- (1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle  
 (2) Pulse test: Pulse width  $\leq 5\text{ ms}$

| <b>THERMAL CHARACTERISTICS</b> ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted) |                          |           |                    |
|---|--------------------------|-----------|--------------------|
| PARAMETER   | SYMBOL                   | V20DM103C | UNIT               |
| Typical thermal resistance per device   | $R_{\theta JC}^{(1)}$    | 1.8       | $^\circ\text{C/W}$ |
|   | $R_{\theta JA}^{(2)(3)}$ | 58        |                    |

**Notes**

- (1) Mounted on infinite heatsink  
 (2) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$   
 (3) Free air, without heatsink

| <b>ORDERING INFORMATION</b> (Example) |                 |              |               |                                    |
|---------------------------------------|-----------------|--------------|---------------|------------------------------------|
| PREFERRED P/N                         | UNIT WEIGHT (g) | PACKAGE CODE | BASE QUANTITY | DELIVERY MODE                      |
| V20DM103C-M3/I                        | 0.55            | I            | 2000/reel     | 13" diameter plastic tape and reel |
| V20DM103CHM3/I (1)                    | 0.55            | I            | 2000/reel     | 13" diameter plastic tape and reel |

**Note**

- (1) AEC-Q101 qualified

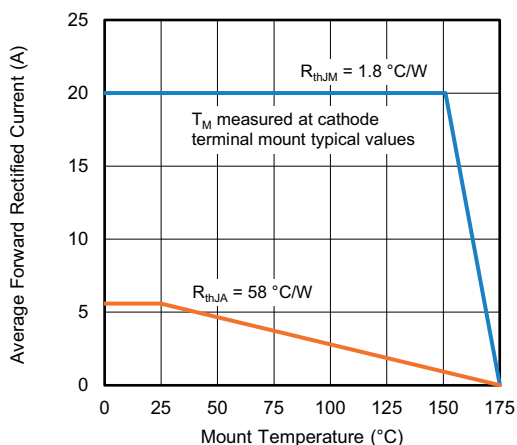
**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^\circ\text{C}$  unless otherwise noted)


Fig. 1 - Maximum Forward Current Derating Curve

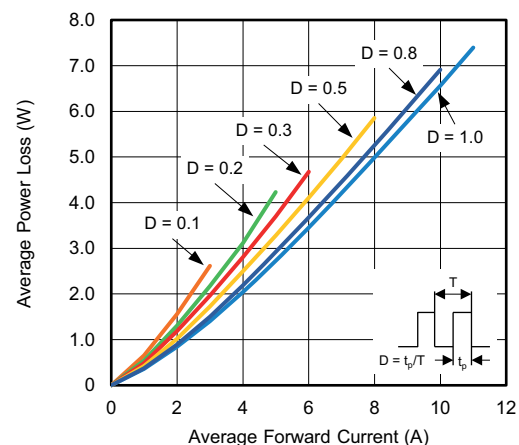


Fig. 2 - Average Power Loss Characteristics

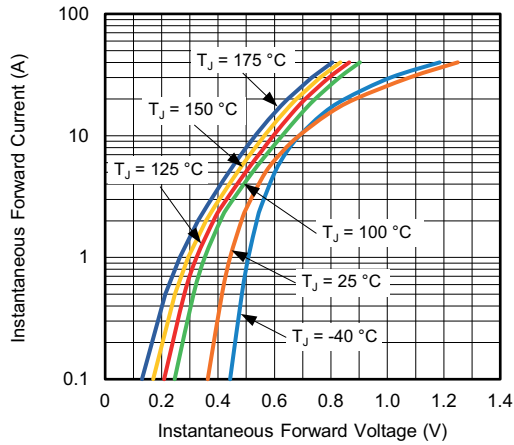


Fig. 3 - Typical Instantaneous Forward Characteristics

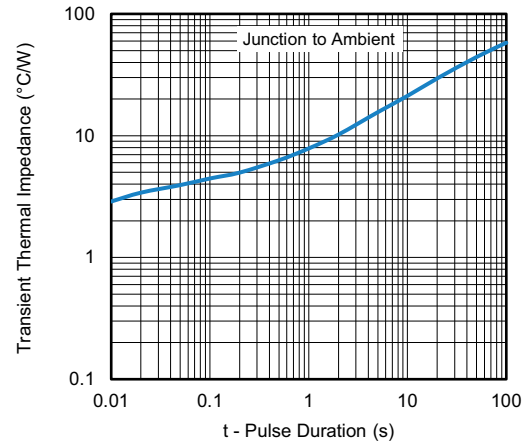


Fig. 6 - Typical Transient Thermal Impedance

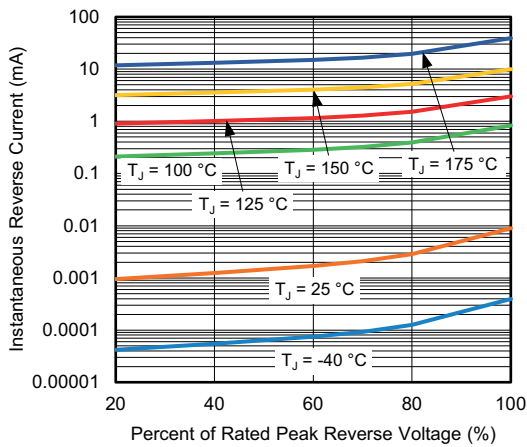


Fig. 4 - Typical Reverse Leakage Characteristics

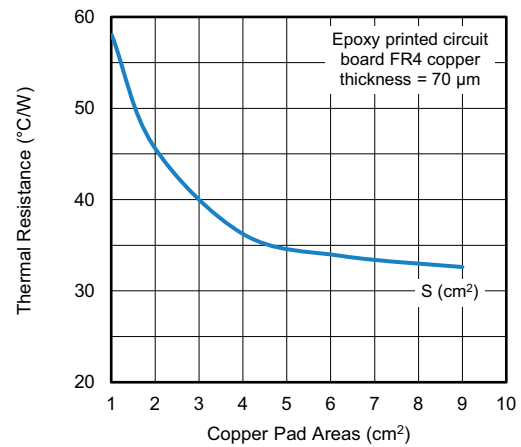


Fig. 7 - Thermal Resistance Junction-to-Ambient vs. Copper Pad Areas

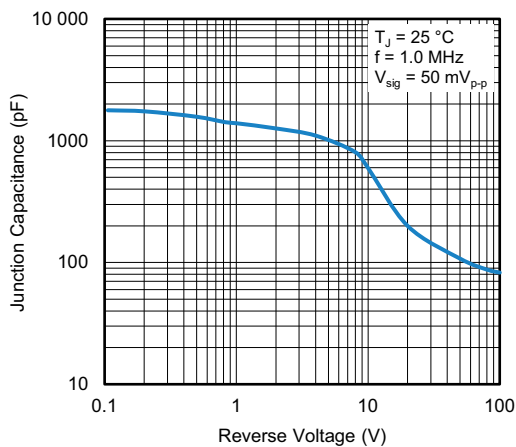
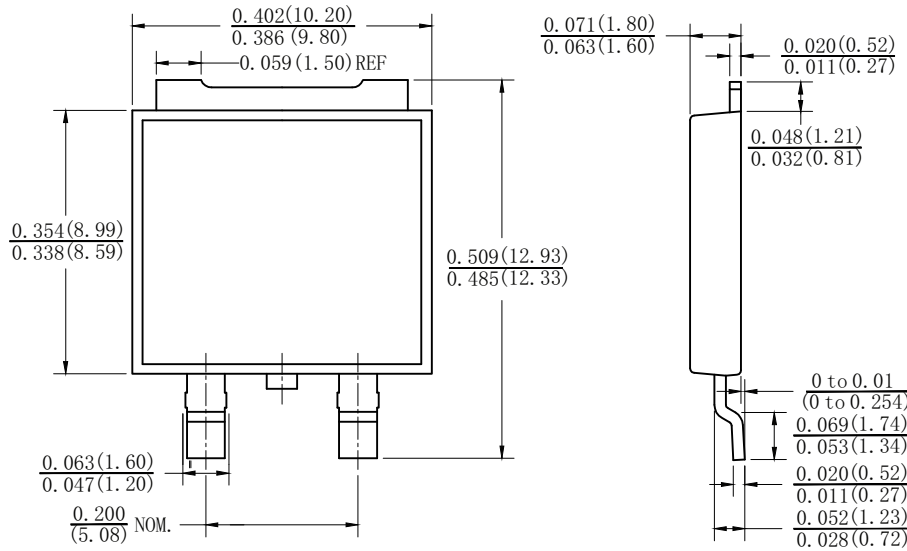


Fig. 5 - Typical Junction Capacitance

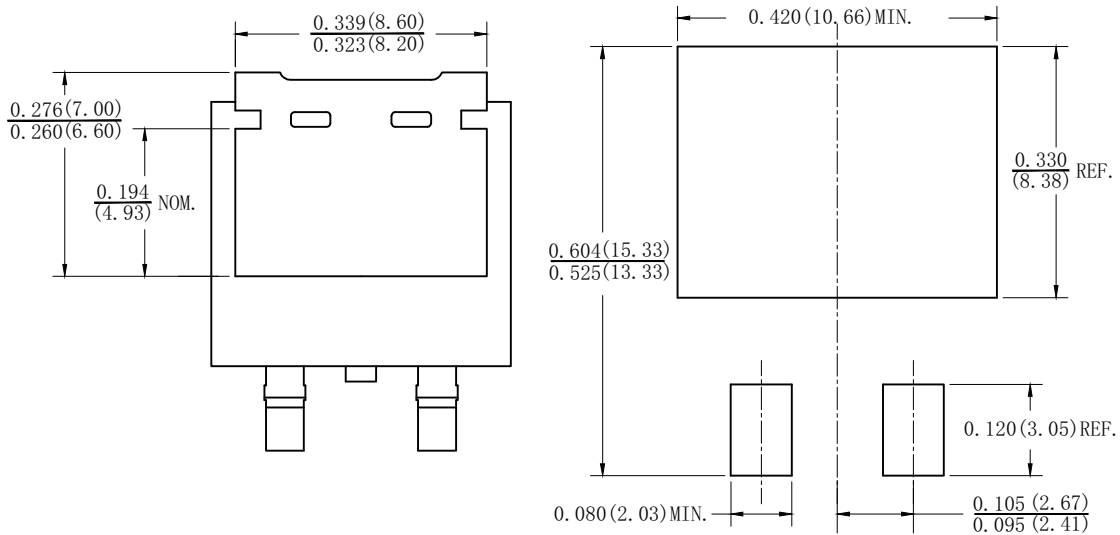


PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

SMPD (TO-263AC)



Mounting Pad Layout





## Disclaimer

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